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INTERNATIONAL CONFERENCE ON SOLID STATE DEVICES AND MATERIALS

ssdm 2026

Sep. 14-17, 2026
Dejima Messe Nagasaki

Plenary Session

Julien Ryckaert
(imec)
CMOS 2.0:
The Vertical Turn in Scaling

Yoshihisa Kagawa
(Sony Semiconductor Solutions Corporation)
Current Trends of 3D Integrated
CMOS Image Sensors
(tentative)

Heike Riel
(IBM Research)
TDB

Special Talk Session

Masataka Osaki
(NVIDIA)

Dejima Messe Nagasaki

Scope of Conference

1. Advanced CMOS: Material Science / Process Engineering / Device Technology
2. Advanced and Emerging Memories / New Applications
3. Heterogeneous and 3D Integration / Interconnect / MEMS
4. Power / High-speed Devices and Materials
5. Photonics: Devices / Integration / Related Technology
6. Energy Harvesting and Converting Devices and Materials
7. Organic / Molecular / Bio-electronics
8. Low Dimensional Devices and Materials
9. Novel Functional / Quantum / Spintronic Devices and Materials
10. Thin Film Electronics: Oxide / Non-single Crystalline / Novel Process
11. Advanced Materials: Synthesis / Crystal Growth / Characterization
12. Advanced and Innovative Circuits / Systems Interacting with Devices and Materials

Conference Chairs

Organizing : M. Hatano (Science Tokyo)
Program : O. Nakatsuka (Nagoya Univ.)
Steering : K. Nagashio (The Univ. of Tokyo)

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